TRANSMITTAL FORM

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> January 14, 2002 (Date of Deposit)

Box Patent Application Assistant Commissioner For Patents Washington, D.C. 20231

Attorney Doc. #: 67,200-641 Mailing Date:

Jan. 14, 2002

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s):

Chih-Ming Ke

Tsai-Sheng Gau

Jaw-Jung Shin

Anthony Yen

For:

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Reducing Photoresist Shrinkage Via Plasma Treatment

Submitted herewith are:

_ 3 sheets of formal drawings showing Figs 1-4

An Assignment of the invention to Taiwan Semiconductor Manufacturing Co., Ltd., together with Assignment Recordal Sheet

A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$370.00	\$740.00	\$740.00
Total Claims	20x20	0 x	\$9.00	\$18.00	\$0
Indep. Claims	3 -3	0 x	\$42.00	\$84.00	\$0
Multiple Dep. Clms.			\$140.00	\$280.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$780.00